

AMENDMENTS TO THE SPECIFICATION

Please replace the present Abstract of the Disclosure with the following amended Abstract of the Disclosure (a copy of the amended Abstract which can be substituted into the application is attached):

~~A laminate which is advantageously used as an insulating layer for electronic package application and as an adhesive film for fixing a semiconductor wafer for semiconductor device application, laminates comprising the same and a process for manufacturing the above laminate.~~

~~The laminate (I) comprises a base layer (A) and an adhesive layer (B) formed on one side or both sides of the layer A, the layer A is a film made of (A-1) a specific wholly aromatic polyimide (PI^{A-1}) or (A-2) a specific wholly aromatic polyamide (PA^{A-2}); and the layer B comprises (B-1) a specific wholly aromatic polyimide (PI^{B-1}), (B-2) a specific wholly aromatic polyamide (PA^{B-2}), or (B-3) a specific resin composition (RC^{B-3}) comprising a wholly aromatic polyimide (PI^{B-3}) and a specific wholly aromatic polyamide (PA^{B-3}), laminates comprising the same and a process for manufacturing the above laminate.~~

A laminate which is advantageously used as an insulating layer for electronic package application and as an adhesive film for fixing a semiconductor wafer for semiconductor device application, laminates comprising the same and a process for manufacturing the above laminate.
The laminate (I) comprises a base layer (A) and an adhesive layer (B) formed on one side or both sides of the layer A, the layer A is a film made of (A-1) a specific wholly aromatic polyimide (PI^{A-1}) or (A-2) a specific wholly aromatic polyamide (PA^{A-2}); and the layer B comprises (B-1) a specific wholly aromatic polyimide (PI^{B-1}), (B-2) a specific wholly aromatic polyamide (PA^{B-2}), or (B-3) a specific resin composition (RC^{B-3}) comprising a wholly aromatic polyimide (PI^{B-3}) and

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a specific wholly aromatic polyamide (PA^{B-3}), laminates comprising the same and a process for
manufacturing the above laminate.